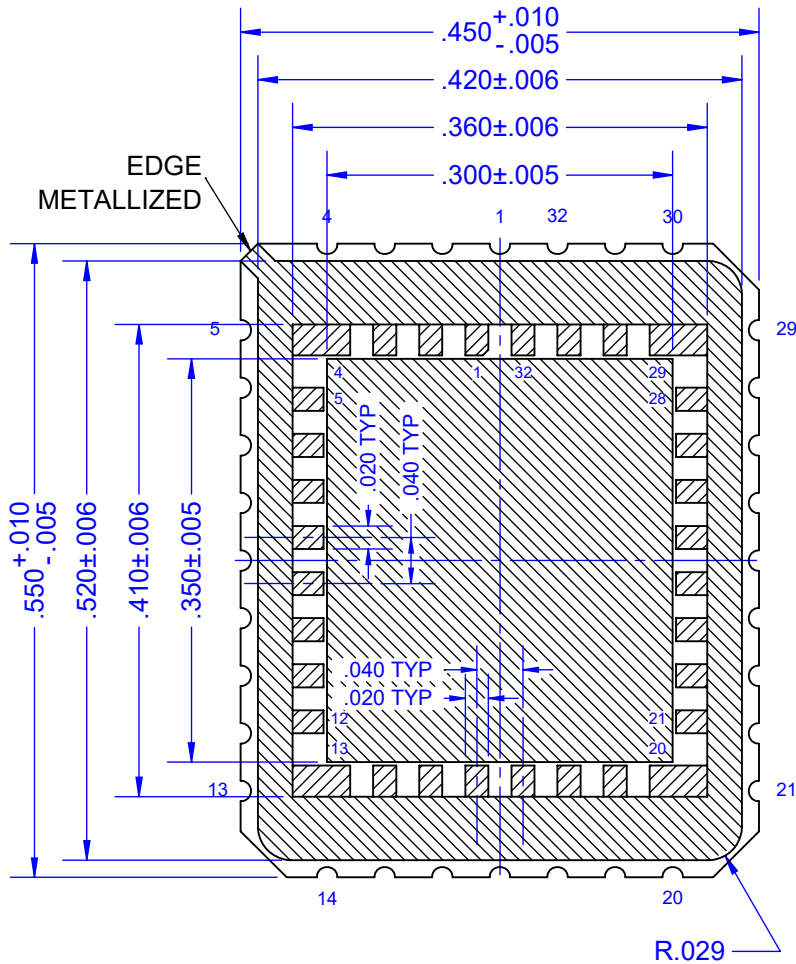
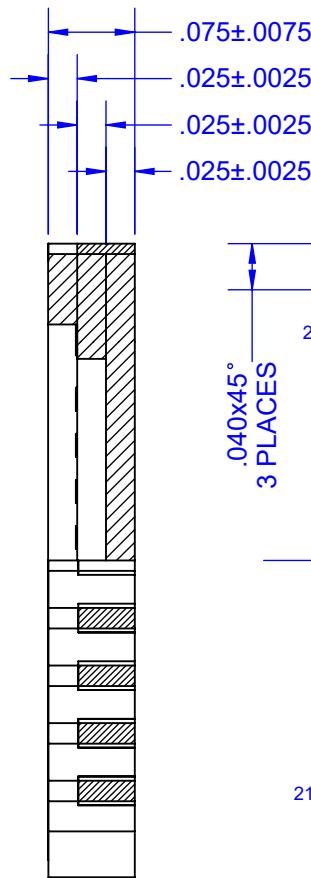


NON-MAGNETIC

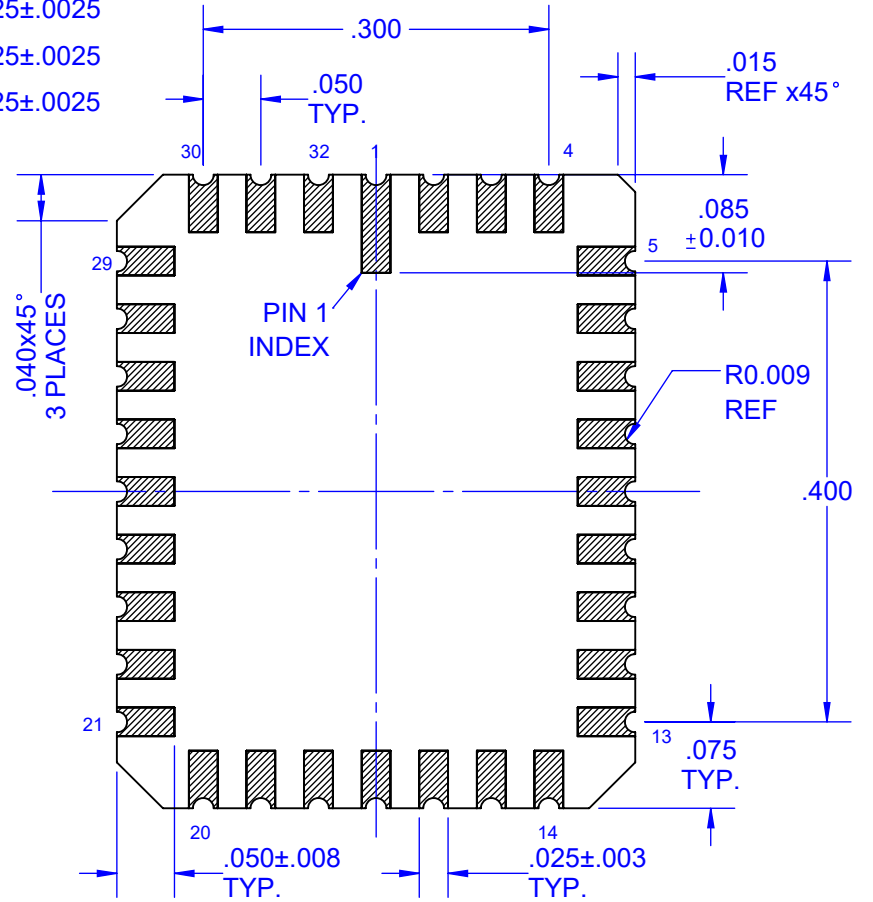
TOP VIEW



SIDE VIEW



BOTTOM VIEW



NOTES: (Unless Otherwise Specified).

1) DIMENSIONS in INCH.

2) PLATING:

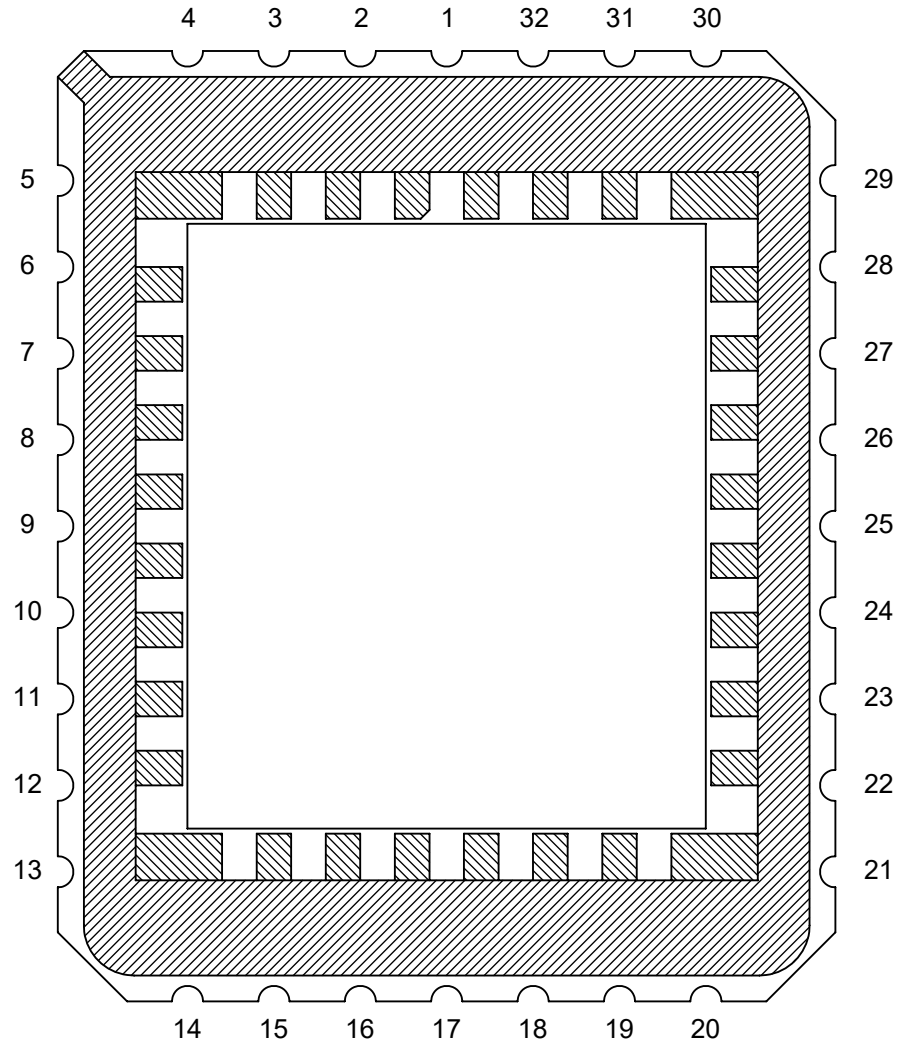
Ni = NONE

Au 20 Micro-inch ($0.5\mu\text{m}$) Min.

3) SEAL RING AND DIE ATTACH SHALL BE ISOLATED FROM ALL LEADS.

APPROVALS	DATE				
DRAWN T. Au	4/17/2022				
ENG M. Hart	4/17/2022	TITLE LCC32B50R.45x.55-NM300x350 NON-MAGNETIC			
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		6:1	A	143202	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 4
REVISED					

BOND PAD DIAGRAM



TopLine®

TITLE LCC32B50R.45x.55-NM300x350
NON-MAGNETIC

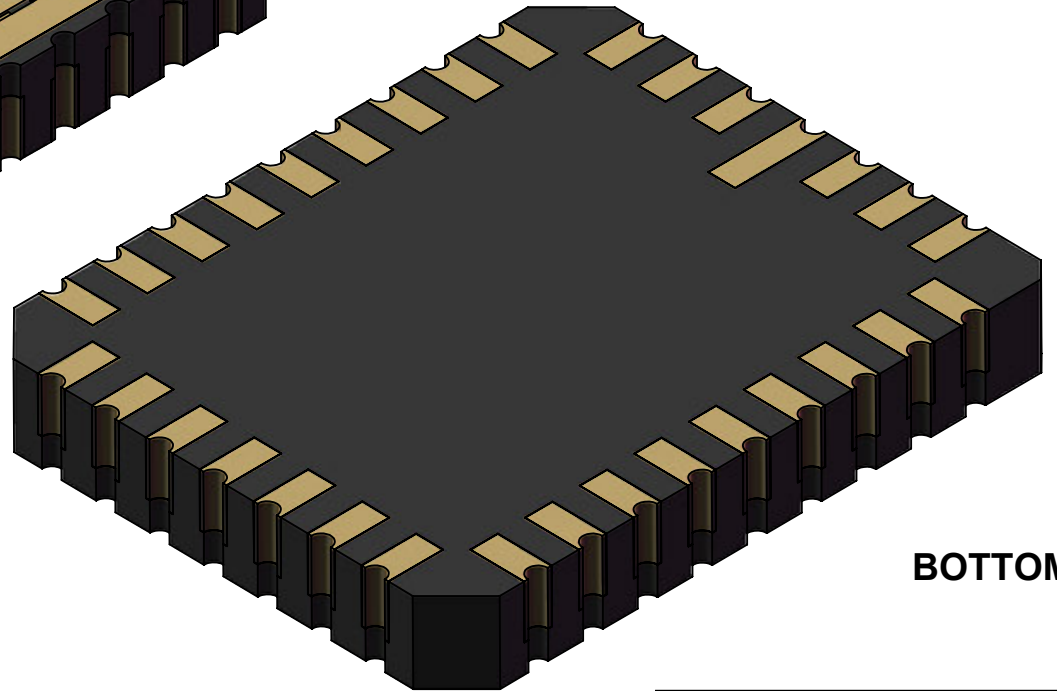
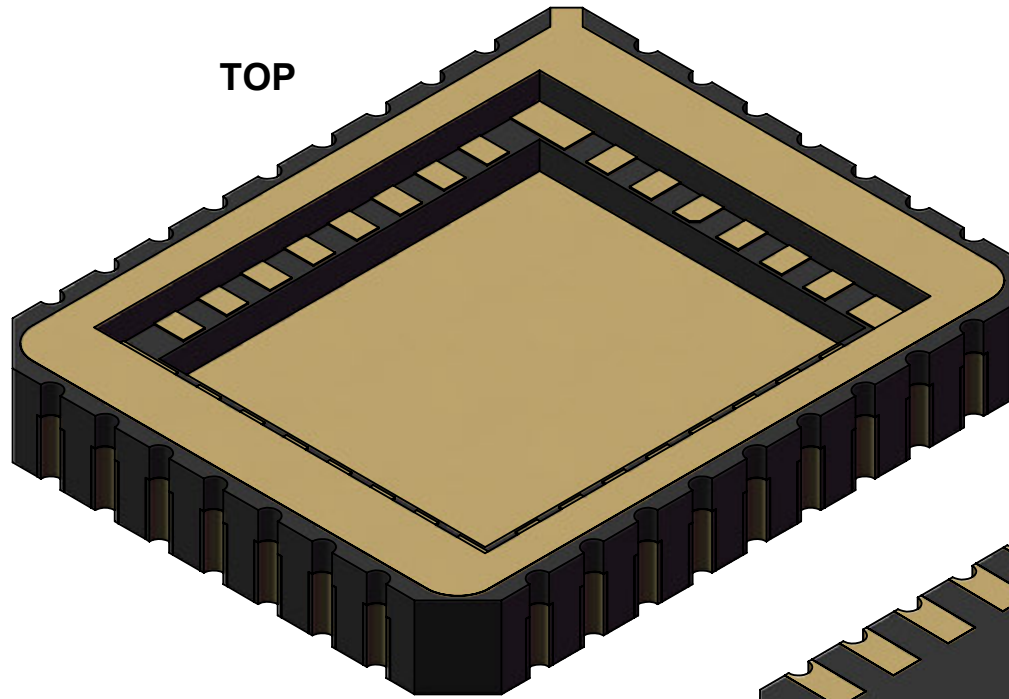
SCALE 9:1	SIZE A	DRAWING NO. 143202	REV A
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DO NOT SCALE DRAWING

SHEET 2 OF 4

MODEL

TOP



BOTTOM

TopLine[®]

TITLE LCC32B50R.45x.55-NM300x350
NON-MAGNETIC

SCALE	SIZE	DRAWING NO.	REV
8:1	A	143202	A

DO NOT SCALE DRAWING

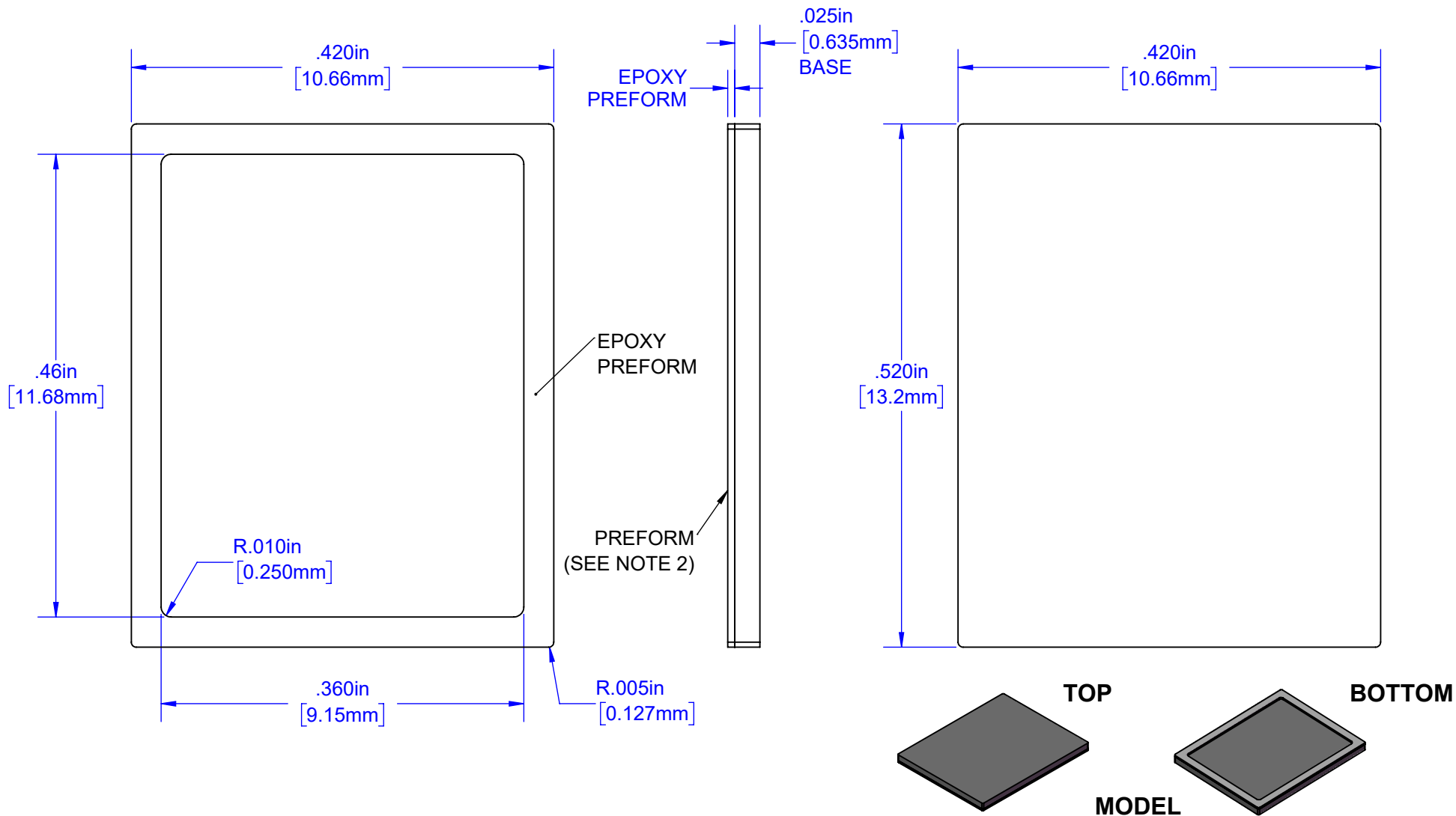
SHEET 3 OF 4

CERAMIC LID (OPTIONAL)

BOTTOM

SIDE

TOP



NOTES:

1. BASE MATERIAL: BLACK CERAMIC Al_2O_3 .
2. Epoxy Preform (B-STAGE) Thickness: 0.003~0.007in [0.076~0.18mm].
3. TOLERANCE: ± 0.005 in (0.127mm).

TopLine[®]			
TITLE B-CLID-420x520-A CERAMIC LID WITH EPOXY PREFORM			
SCALE 3:1	SIZE A	DRAWING NO. 143202	REV A
DO NOT SCALE DRAWING		SHEET 4 OF 4	